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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c622a-20i-ss

Table of Contents

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4.0 MEMORY ORGANIZATION

4.1 Program Memory Organization

The PIC16C62X has a 13-bit program counter capable of addressing an 8K x 14 program memory space. Only the first 512 x 14 (0000h - 01FFh) for the PIC16C620(A) and PIC16CR620, 1K x 14 (0000h - 03FFh) for the PIC16C621(A) and 2K x 14 (0000h - 07FFh) for the PIC16C622(A) are physically implemented. Accessing a location above these boundaries will cause a wrap-around within the first 512 x 14 space (PIC16C(R)620(A)) or 1K x 14 space (PIC16C621(A)) or 2K x 14 space (PIC16C622(A)). The RESET vector is at 0000h and the interrupt vector is at 0004h (Figure 4-1, Figure 4-2, Figure 4-3).

FIGURE 4-1: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C620/PIC16C620A/ PIC16CR620A

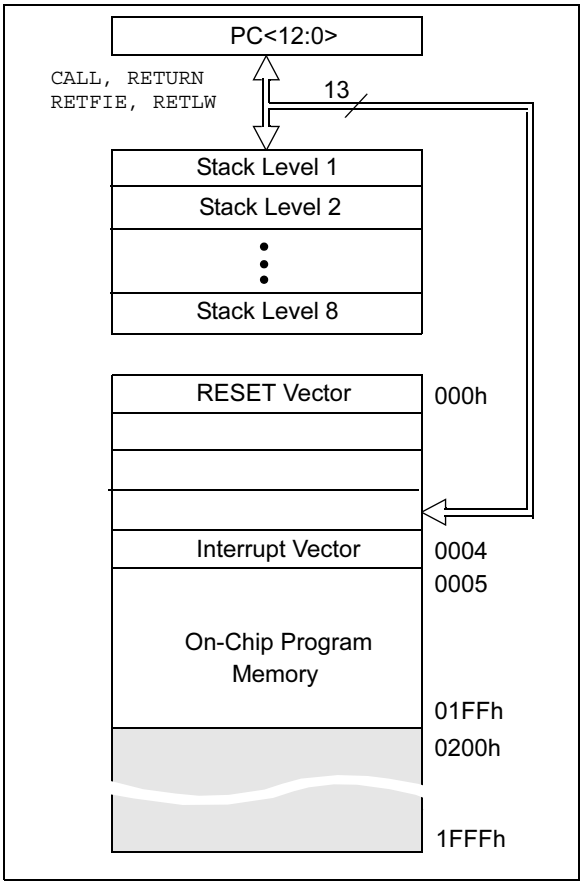


FIGURE 4-2: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C621/PIC16C621A

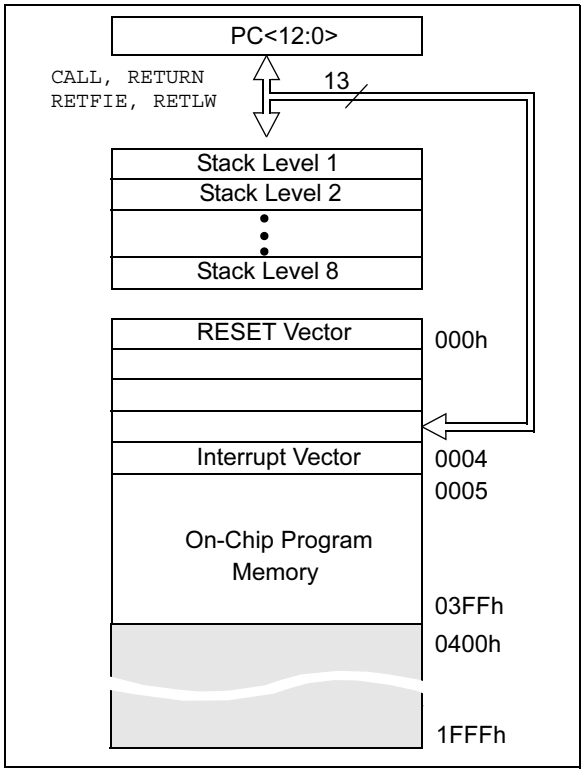
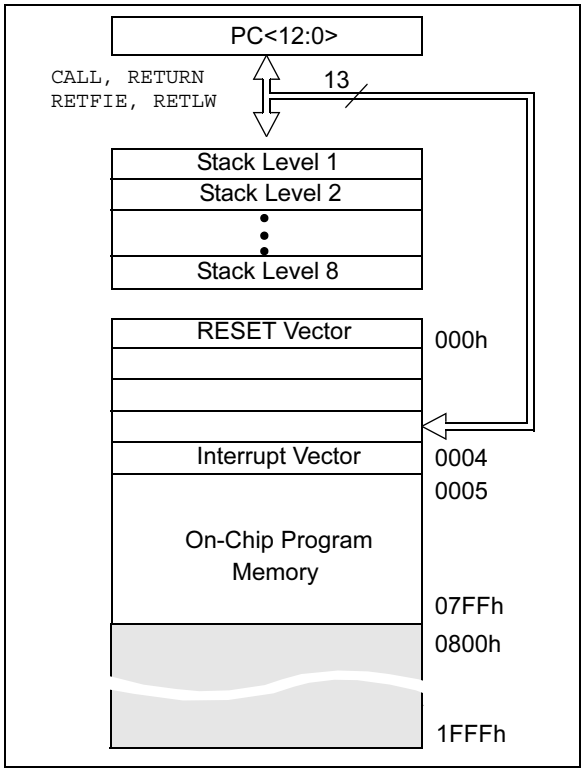


FIGURE 4-3: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C622/PIC16C622A



5.0 I/O PORTS

The PIC16C62X have two ports, PORTA and PORTB. Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

5.1 PORTA and TRISA Registers

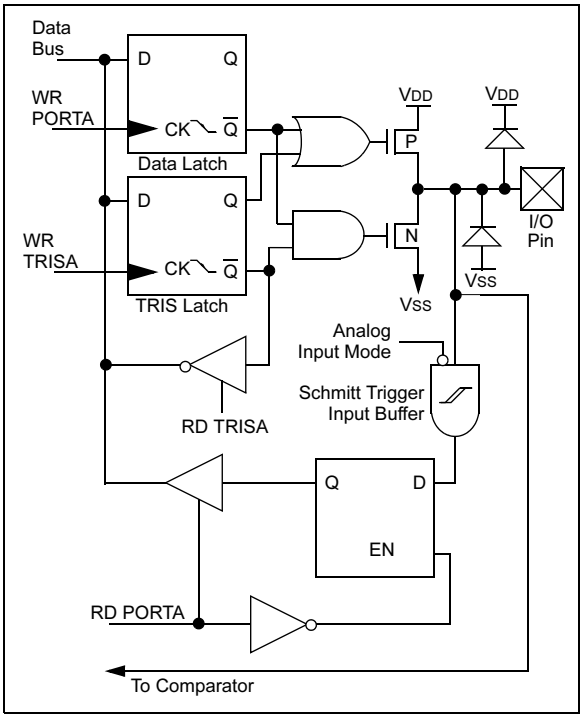
PORTA is a 5-bit wide latch. RA4 is a Schmitt Trigger input and an open drain output. Port RA4 is multiplexed with the T0CKI clock input. All other RA port pins have Schmitt Trigger input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers), which can configure these pins as input or output.

A '1' in the TRISA register puts the corresponding output driver in a Hi-impedance mode. A '0' in the TRISA register puts the contents of the output latch on the selected pin(s).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

The PORTA pins are multiplexed with comparator and voltage reference functions. The operation of these pins are selected by control bits in the CMCON (comparator control register) register and the VRCON (voltage reference control register) register. When selected as a comparator input, these pins will read as '0's.

FIGURE 5-1: BLOCK DIAGRAM OF RA1:RA0 PINS



Note:	On RESET, the TRISA register is set to all inputs. The digital inputs are disabled and the comparator inputs are forced to ground to reduce excess current consumption.

TRISA controls the direction of the RA pins, even when they are being used as comparator inputs. The user must make sure to keep the pins configured as inputs when using them as comparator inputs.

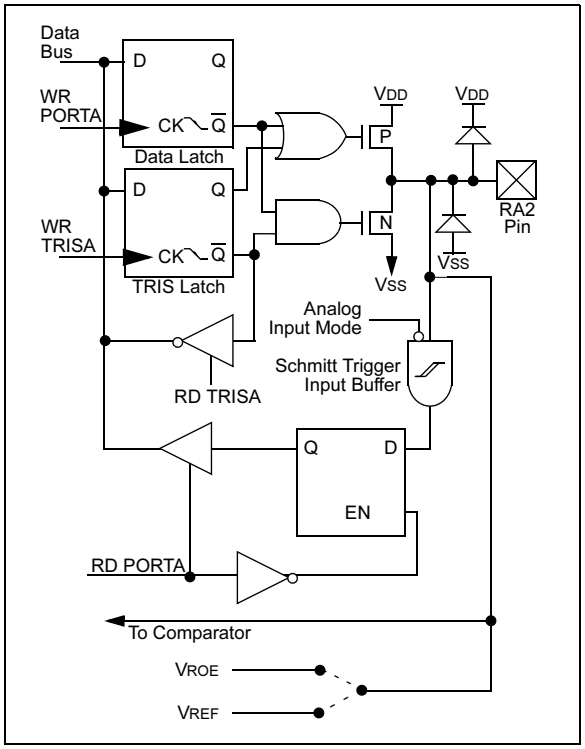
The RA2 pin will also function as the output for the voltage reference. When in this mode, the VREF pin is a very high impedance output and must be buffered prior to any external load. The user must configure TRISA<2> bit as an input and use high impedance loads.

In one of the Comparator modes defined by the CMCON register, pins RA3 and RA4 become outputs of the comparators. The TRISA<4:3> bits must be cleared to enable outputs to use this function.

EXAMPLE 5-1: INITIALIZING PORTA

```
CLRF    PORTA           ;Initialize PORTA by setting
                        ;output data latches
MOVLW   0X07            ;Turn comparators off and
MOVWF   CMCON           ;enable pins for I/O
                        ;functions
BSF     STATUS, RP0     ;Select Bank1
MOVLW   0x1F            ;Value used to initialize
                        ;data direction
MOVWF   TRISA           ;Set RA<4:0> as inputs
                        ;TRISA<7:5> are always
                        ;read as '0'.
```

FIGURE 5-2: BLOCK DIAGRAM OF RA2 PIN



NOTES:

The code example in Example 7-1 depicts the steps required to configure the comparator module. RA3 and RA4 are configured as digital output. RA0 and RA1 are configured as the V- inputs and RA2 as the V+ input to both comparators.

EXAMPLE 7-1: INITIALIZING COMPARATOR MODULE

```
MOVLW   0x03          ;Init comparator mode
MOVWF   CMCON         ;CM<2:0> = 011
CLRF    PORTA         ;Init PORTA
BSF     STATUS,RP0    ;Select Bank1
MOVLW   0x07          ;Initialize data direction
MOVWF   TRISA         ;Set RA<2:0> as inputs
                      ;RA<4:3> as outputs
                      ;TRISA<7:5> always read '0'
BCF     STATUS,RP0    ;Select Bank 0
CALL    DELAY 10      ;10µs delay
MOVF    CMCON,F       ;Read CMCON to end change condition
BCF     PIR1,CMIF     ;Clear pending interrupts
BSF     STATUS,RP0    ;Select Bank 1
BSF     PIE1,CMIE     ;Enable comparator interrupts
BCF     STATUS,RP0    ;Select Bank 0
BSF     INTCON,PEIE   ;Enable peripheral interrupts
BSF     INTCON,GIE    ;Global interrupt enable
```

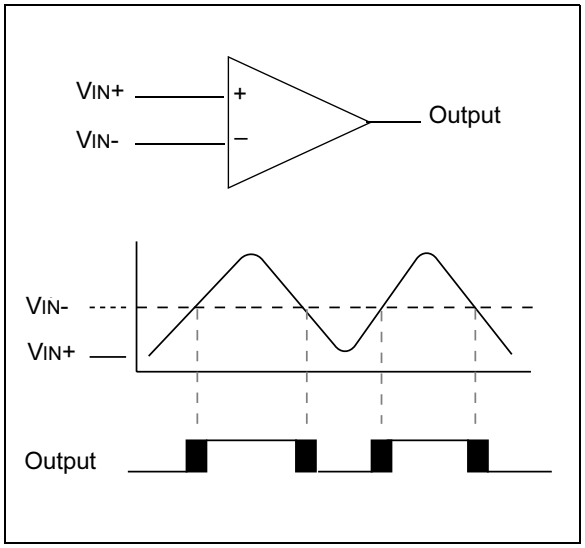
7.2 Comparator Operation

A single comparator is shown in Figure 7-2 along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input VIN-, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input VIN-, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 7-2 represent the uncertainty due to input offsets and response time.

7.3 Comparator Reference

An external or internal reference signal may be used depending on the comparator Operating mode. The analog signal that is present at VIN- is compared to the signal at VIN+, and the digital output of the comparator is adjusted accordingly (Figure 7-2).

FIGURE 7-2: SINGLE COMPARATOR



7.3.1 EXTERNAL REFERENCE SIGNAL

When external voltage references are used, the comparator module can be configured to have the comparators operate from the same or different reference sources. However, threshold detector applications may require the same reference. The reference signal must be between VSS and VDD, and can be applied to either pin of the comparator(s).

7.3.2 INTERNAL REFERENCE SIGNAL

The comparator module also allows the selection of an internally generated voltage reference for the comparators. Section 10, Instruction Sets, contains a detailed description of the Voltage Reference Module that provides this signal. The internal reference signal is used when the comparators are in mode CM<2:0>=010 (Figure 7-1). In this mode, the internal voltage reference is applied to the VIN+ pin of both comparators.

8.0 VOLTAGE REFERENCE MODULE

The Voltage Reference is a 16-tap resistor ladder network that provides a selectable voltage reference. The resistor ladder is segmented to provide two ranges of VREF values and has a power-down function to conserve power when the reference is not being used. The VRCON register controls the operation of the reference as shown in Register 8-1. The block diagram is given in Figure 8-1.

8.1 Configuring the Voltage Reference

The Voltage Reference can output 16 distinct voltage levels for each range. The equations used to calculate the output of the Voltage Reference are as follows:

if VRR = 1: VREF = (VR<3:0>/24) x VDD

if VRR = 0: VREF = (VDD x 1/4) + (VR<3:0>/32) x VDD

The setting time of the Voltage Reference must be considered when changing the VREF output (Table 12-1). Example 8-1 shows an example of how to configure the Voltage Reference for an output voltage of 1.25V with VDD = 5.0V.

REGISTER 8-1: VRCON REGISTER(ADDRESS 9Fh)

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
VREN	VROE	VRR	—	VR3	VR2	VR1	VR0
bit 7							bit 0

bit 7 **VREN:** VREF Enable
1 = VREF circuit powered on
0 = VREF circuit powered down, no IDD drain

bit 6 **VROE:** VREF Output Enable
1 = VREF is output on RA2 pin
0 = VREF is disconnected from RA2 pin

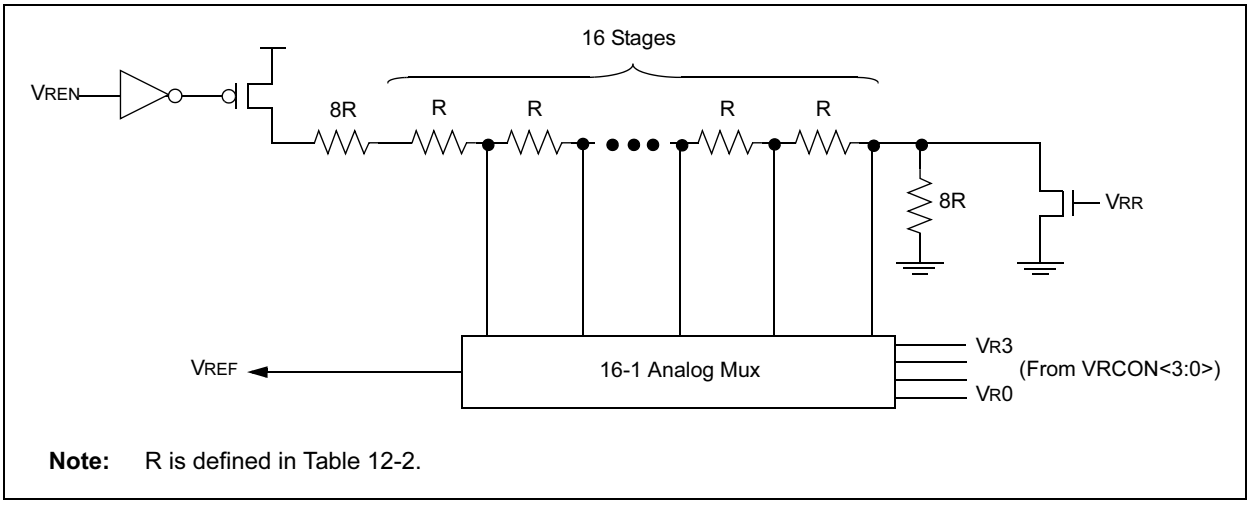
bit 5 **VRR:** VREF Range selection
1 = Low Range
0 = High Range

bit 4 **Unimplemented:** Read as '0'

bit 3-0 **VR<3:0>**: VREF value selection 0 ≤ VR [3:0] ≤ 15
when VRR = 1: VREF = (VR<3:0>/ 24) * VDD
when VRR = 0: VREF = 1/4 * VDD + (VR<3:0>/ 32) * VDD

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

FIGURE 8-1: VOLTAGE REFERENCE BLOCK DIAGRAM



Note: R is defined in Table 12-2.

9.2 Oscillator Configurations

9.2.1 OSCILLATOR TYPES

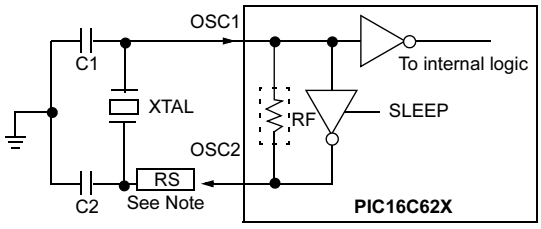
The PIC16C62X devices can be operated in four different oscillator options. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

9.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation (Figure 9-1). The PIC16C62X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1 pin (Figure 9-2).

FIGURE 9-1: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (HS, XT OR LP OSC CONFIGURATION)



See Table 9-1 and Table 9-2 for recommended values of C1 and C2.

Note: A series resistor may be required for AT strip cut crystals.

FIGURE 9-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

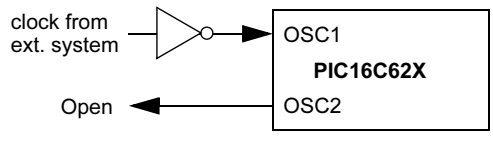


TABLE 9-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Ranges Characterized:			
Mode	**Freq**	**OSC1(C1)**	**OSC2(C2)**
XT	455 kHz 2.0 MHz 4.0 MHz	22 - 100 pF 15 - 68 pF 15 - 68 pF	22 - 100 pF 15 - 68 pF 15 - 68 pF
HS	8.0 MHz 16.0 MHz	10 - 68 pF 10 - 22 pF	10 - 68 pF 10 - 22 pF

Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

TABLE 9-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Mode	Freq	OSC1(C1)	OSC2(C2)
LP	32 kHz 200 kHz	68 - 100 pF 15 - 30 pF	68 - 100 pF 15 - 30 pF
XT	100 kHz 2 MHz 4 MHz	68 - 150 pF 15 - 30 pF 15 - 30 pF	150 - 200 pF 15 - 30 pF 15 - 30 pF
HS	8 MHz 10 MHz 20 MHz	15 - 30 pF 15 - 30 pF 15 - 30 pF	15 - 30 pF 15 - 30 pF 15 - 30 pF

Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

9.4.5 TIME-OUT SEQUENCE

On power-up the time-out sequence is as follows: First PWRT time-out is invoked after POR has expired. Then OST is activated. The total time-out will vary based on oscillator configuration and PWRTE bit status. For example, in RC mode with PWRTE bit erased (PWRT disabled), there will be no time-out at all. Figure 9-8, Figure 9-9 and Figure 9-10 depict time-out sequences.

Since the time-outs occur from the POR pulse, if MCLR is kept low long enough, the time-outs will expire. Then bringing MCLR high will begin execution immediately (see Figure 9-9). This is useful for testing purposes or to synchronize more than one PIC16C62X device operating in parallel.

Table 9-4 shows the RESET conditions for some special registers, while Table 9-5 shows the RESET conditions for all the registers.

9.4.6 POWER CONTROL (PCON)/ STATUS REGISTER

The power control/STATUS register, PCON (address 8Eh), has two bits.

Bit0 is BOR (Brown-out). BOR is unknown on Power-on Reset. It must then be set by the user and checked on subsequent RESETS to see if BOR = 0, indicating that a brown-out has occurred. The BOR STATUS bit is a don't care and is not necessarily predictable if the brown-out circuit is disabled (by setting BODEN bit = 0 in the Configuration word).

Bit1 is POR (Power-on Reset). It is a '0' on Power-on Reset and unaffected otherwise. The user must write a '1' to this bit following a Power-on Reset. On a subsequent RESET, if POR is '0', it will indicate that a Power-on Reset must have occurred (V_{DD} may have gone too low).

TABLE 9-1: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out Reset	Wake-up from SLEEP
	PWRTE = 0	PWRTE = 1		
XT, HS, LP	72 ms + 1024 TOSC	1024 TOSC	72 ms + 1024 TOSC	1024 TOSC
RC	72 ms	—	72 ms	—

TABLE 9-2: STATUS/PCON BITS AND THEIR SIGNIFICANCE

POR	BOR	TO	PD	
0	X	1	1	Power-on Reset
0	X	0	X	Illegal, TO is set on POR
0	X	X	0	Illegal, PD is set on POR
1	0	X	X	Brown-out Reset
1	1	0	u	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	MCLR Reset during normal operation
1	1	1	0	MCLR Reset during SLEEP

Legend: u = unchanged, x = unknown

TABLE 9-3: SUMMARY OF REGISTERS ASSOCIATED WITH BROWN-OUT

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other RESETS(1)
83h	STATUS				TO	PD				0001 1xxx	000q quuu
8Eh	PCON	—	—	—	—	—	—	POR	BOR	---- --0x	---- --uq

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0', q = value depends on condition.

Note 1: Other (non Power-up) Resets include MCLR Reset, Brown-out Reset and Watchdog Timer Reset during normal operation.

SUBLW **Subtract W from Literal**

Syntax: [*label*] SUBLW k

Operands: $0 \le k \le 255$

Operation: k - (W) → (W)

Status Affected: C, DC, Z

Encoding:

11	110x	kkkk	kkkk

Description: The W register is subtracted (2's complement method) from the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example 1:
```
SUBLW   0x02
```
Before Instruction
W = 1
C = ?
After Instruction
W = 1
C = 1; result is positive

Example 2: Before Instruction
W = 2
C = ?
After Instruction
W = 0
C = 1; result is zero

Example 3: Before Instruction
W = 3
C = ?
After Instruction
W = 0xFF
C = 0; result is negative

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - (W) → (dest)

Status Affected: C, DC, Z

Encoding:

00	0010	dfff	ffff

Description: Subtract (2's complement method) W register from register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example 1:
```
SUBWF   REG1,1
```
Before Instruction
REG1= 3
W = 2
C = ?
After Instruction
REG1= 1
W = 2
C = 1; result is positive

Example 2: Before Instruction
REG1= 2
W = 2
C = ?
After Instruction
REG1= 0
W = 2
C = 1; result is zero

Example 3: Before Instruction
REG1= 1
W = 2
C = ?
After Instruction
REG1= 0xFF
W = 2
C = 0; result is negative

SWAPF **Swap Nibbles in f**

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f<3:0>) → (dest<7:4>),
(f<7:4>) → (dest<3:0>)

Status Affected: None

Encoding:

00	1110	dfff	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in W register. If 'd' is 1, the result is placed in register 'f'.

Words: 1

Cycles: 1

Example
```
SWAPF REG, 0
```
Before Instruction
REG1 = 0xA5

After Instruction
REG1 = 0xA5
W = 0x5A

TRIS **Load TRIS Register**

Syntax: [*label*] TRIS f

Operands: $5 \le f \le 7$

Operation: (W) → TRIS register f;

Status Affected: None

Encoding:

00	0000	0110	0fff

Description: The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.

Words: 1

Cycles: 1

Example

To maintain upward compatibility with future PICmicro® products, do not use this instruction.

XORLW **Exclusive OR Literal with W**

Syntax: [*label*] XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. k → (W)

Status Affected: Z

Encoding:

11	1010	kkkk	kkkk

Description: The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example
```
XORLW 0xAF
```
Before Instruction
W = 0xB5

After Instruction
W = 0x1A

XORWF **Exclusive OR W with f**

Syntax: [*label*] XORWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .XOR. (f) → (dest)

Status Affected: Z

Encoding:

00	0110	dfff	ffff

Description: Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
XORWF REG 1
```
Before Instruction
REG = 0xAF
W = 0xB5

After Instruction
REG = 0x1A
W = 0xB5

NOTES:

12.1 DC Characteristics: PIC16C62X-04 (Commercial, Industrial, Extended) PIC16C62X-20 (Commercial, Industrial, Extended) PIC16LC62X-04 (Commercial, Industrial, Extended) (CONT.)

PIC16C62X			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LC62X			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended Operating voltage VDD range is the PIC16C62X range.				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D022	ΔIWDT	WDT Current(5)	—	6.0	20	µA	VDD=4.0V
					25	µA	(125°C)
D022A	ΔIBOR	Brown-out Reset Current(5)	—	350	425	µA	BOD enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator(5)	—	—	100	µA	VDD = 4.0V
D023A	ΔIVREF	VREF Current(5)	—	—	300	µA	VDD = 4.0V
D022	ΔIWDT	WDT Current(5)	—	6.0	15	µA	VDD=3.0V
D022A	ΔIBOR	Brown-out Reset Current(5)	—	350	425	µA	BOD enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator(5)	—	—	100	µA	VDD = 3.0V
D023A	ΔIVREF	VREF Current(5)	—	—	300	µA	VDD = 3.0V
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in Active Operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

12.2 DC Characteristics: PIC16C62XA-04 (Commercial, Industrial, Extended) PIC16C62XA-20 (Commercial, Industrial, Extended) PIC16LC62XA-04 (Commercial, Industrial, Extended) (CONT.)

PIC16C62XA			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LC62XA			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D010	IDD	Supply Current(2, 4)	—	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, **(Note 4)***
			—	0.4	1.2	mA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT mode, **(Note 4)***
			—	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS mode, **(Note 6)**
			—	4.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS mode
			—	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS mode
			—	35	70	µA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D010	IDD	Supply Current(2)	—	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, **(Note 4)***
			—	—	1.1	mA	FOSC = 4 MHz, VDD = 2.5V, WDT disabled, XT mode, **(Note 4)**
			—	35	70	µA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode
D020	IPD	Power-down Current(3)	—	—	2.2	µA	VDD = 3.0V
			—	—	5.0	µA	VDD = 4.5V*
			—	—	9.0	µA	VDD = 5.5V
			—	—	15	µA	VDD = 5.5V Extended Temp.
D020	IPD	Power-down Current(3)	—	—	2.0	µA	VDD = 2.5V
			—	—	2.2	µA	VDD = 3.0V*
			—	—	9.0	µA	VDD = 5.5V
			—	—	15	µA	VDD = 5.5V Extended Temp.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in Active Operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

12.3 DC CHARACTERISTICS: PIC16CR62XA-04 (Commercial, Industrial, Extended) PIC16CR62XA-20 (Commercial, Industrial, Extended) PIC16LCR62XA-04 (Commercial, Industrial, Extended) (CONT.)

PIC16CR62XA-04 **PIC16CR62XA-20**			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LCR62XA-04			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D020	IPD	Power-down Current(3)	—	200	950	nA	VDD = 3.0V
			—	0.400	1.8	µA	VDD = 4.5V*
			—	0.600	2.2	µA	VDD = 5.5V
			—	5.0	9.0	µA	VDD = 5.5V Extended Temp.
D020	IPD	Power-down Current(3)	—	200	850	nA	VDD = 2.5V
			—	200	950	nA	VDD = 3.0V*
			—	0.600	2.2	µA	VDD = 5.5V
			—	5.0	9.0	µA	VDD = 5.5V Extended
D022	ΔIWDT	WDT Current(5)	—	6.0	10	µA	VDD=4.0V
					12	µA	(125°C)
D022A	ΔIBOR	Brown-out Reset Current(5)	—	75	125	µA	BOD enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator(5)	—	30	60	µA	VDD = 4.0V
D023A	ΔIVREF	VREF Current(5)	—	80	135	µA	VDD = 4.0V
D022	ΔIWDT	WDT Current(5)	—	6.0	10	µA	VDD=4.0V
					12	µA	(125°C)
D022A	ΔIBOR	Brown-out Reset Current(5)	—	75	125	µA	BOD enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator(5)	—	30	60	µA	VDD = 4.0V
D023A	ΔIVREF	VREF Current(5)	—	80	135	µA	VDD = 4.0V
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in Active Operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended) (CONT.)

PIC16C62X/C62XA/CR62XA	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended
PIC16LC62X/LC62XA/LCR62XA	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended

Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	VOL	Output Low Voltage					
D080		I/O ports	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40° to +85°C
			—	—	0.6	V	IOL = 7.0 mA, VDD = 4.5V, +125°C
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40° to +85°C
			—	—	0.6	V	IOL = 1.2 mA, VDD = 4.5V, +125°C
	VOH	Output High Voltage(3)					
D090		I/O ports (Except RA4)	VDD-0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40° to +85°C
			VDD-0.7	—	—	V	IOH = -2.5 mA, VDD = 4.5V, +125°C
D092		OSC2/CLKOUT (RC only)	VDD-0.7	—	—	V	IOH = -1.3 mA, VDD = 4.5V, -40° to +85°C
			VDD-0.7	—	—	V	IOH = -1.0 mA, VDD = 4.5V, +125°C
	VOH	Output High Voltage(3)					
D090		I/O ports (Except RA4)	VDD-0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40° to +85°C
			VDD-0.7	—	—	V	IOH = -2.5 mA, VDD = 4.5V, +125°C
D092		OSC2/CLKOUT (RC only)	VDD-0.7	—	—	V	IOH = -1.3 mA, VDD = 4.5V, -40° to +85°C
			VDD-0.7	—	—	V	IOH = -1.0 mA, VDD = 4.5V, +125°C
*D150	VOD	Open-Drain High Voltage			10* 8.5*	V	RA4 pin PIC16C62X, PIC16LC62X RA4 pin PIC16C62XA, PIC16LC62XA, PIC16CR62XA, PIC16LCR62XA
*D150	VOD	Open-Drain High Voltage			10* 8.5*	V	RA4 pin PIC16C62X, PIC16LC62X RA4 pin PIC16C62XA, PIC16LC62XA, PIC16CR62XA, PIC16LCR62XA
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin			15	pF	In XT, HS and LP modes when external clock used to drive OSC1.
D101	CIO	All I/O pins/OSC2 (in RC mode)			50	pF	
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin			15	pF	In XT, HS and LP modes when external clock used to drive OSC1.
D101	CIO	All I/O pins/OSC2 (in RC mode)			50	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

12.6 DC Characteristics: PIC16C620A/C621A/C622A-40(3) (Commercial) PIC16CR620A-40(3) (Commercial)

DC CHARACTERISTICS Power Supply Pins			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial			
Characteristic	**Sym**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
Supply Voltage	VDD	4.5	—	5.5	V	HS Option from 20 - 40 MHz
Supply Current(2)	IDD	— —	5.5 7.7	11.5 16	mA mA	FOSC = 40 MHz, VDD = 4.5V, HS mode FOSC = 40 MHz, VDD = 5.5V, HS mode
HS Oscillator Operating Frequency	FOSC	20	—	40	MHz	OSC1 pin is externally driven, OSC2 pin not connected
Input Low Voltage OSC1	VIL	VSS	—	0.2VDD	V	HS mode, OSC1 externally driven
Input High Voltage OSC1	VIH	0.8VDD	—	VDD	V	HS mode, OSC1 externally driven

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in Active Operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VSS,
T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT disabled, HS mode with OSC2 not connected.

3: For device operation between DC and 20 MHz. See Table 12-1 and Table 12-2.

12.7 AC Characteristics: PIC16C620A/C621A/C622A-40(2) (Commercial) PIC16CR620A-40(2) (Commercial)

AC CHARACTERISTICS All Pins Except Power Supply Pins			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial			
Characteristic	**Sym**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
External CLKIN Frequency	FOSC	20	—	40	MHz	HS mode, OSC1 externally driven
External CLKIN Period	TOSC	25	—	50	ns	HS mode (40), OSC1 externally driven
Clock in (OSC1) Low or High Time	TOSL, TOSH	6	—	—	ns	HS mode, OSC1 externally driven
Clock in (OSC1) Rise or Fall Time	TOSR, TOSF	—	—	6.5	ns	HS mode, OSC1 externally driven
OSC1↑ (Q1 cycle) to Port out valid	TOSH2IOV	—	—	100	ns	—
OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TOSH2IOI	50	—	—	ns	—

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

2: For device operation between DC and 20 MHz. See Table 12-1 and Table 12-2.

TABLE 12-1: COMPARATOR SPECIFICATIONS

Operating Conditions: V_{DD} range as described in Table 12-1, -40°C<T_A<+125°C. Current consumption is specified in Table 12-1.

Characteristics	Sym	Min	Typ	Max	Units	Comments
Input offset voltage			± 5.0	± 10	mV	
Input common mode voltage		0		V_{DD} - 1.5	V	
CMRR		+55*			δβ	
Response Time(1)			150*	400* 600*	ns ns	PIC16C62X(A) PIC16LC62X
Comparator mode change to output valid				10*	μs	

* These parameters are characterized but not tested.

Note 1: Response time measured with one comparator input at (V_{DD} - 1.5)/2, while the other input transitions from V_{SS} to V_{DD}.

TABLE 12-2: VOLTAGE REFERENCE SPECIFICATIONS

Operating Conditions:V_{DD} range as described in Table 12-1, -40°C<T_A<+125°C. Current consumption is specified in Table 12-1.

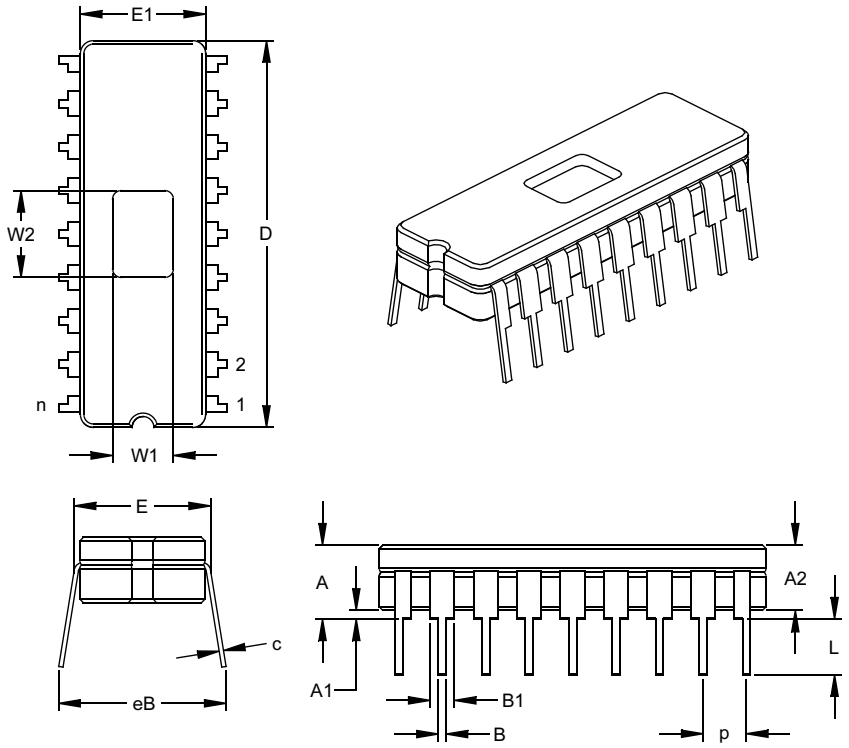
Characteristics	Sym	Min	Typ	Max	Units	Comments
Resolution			V_{DD}/24 V_{DD}/32		LSB LSB	Low Range (V_{RR}=1) High Range (V_{RR}=0)
Absolute Accuracy				±1/4 ±1/2	LSB LSB	Low Range (V_{RR}=1) High Range (V_{RR}=0)
Unit Resistor Value (R)			2K*		Ω	Figure 8-1
Settling Time(1)				10*	μs	

* These parameters are characterized but not tested.

Note 1: Settling time measured while V_{RR} = 1 and V_R<3:0> transitions from 0000 to 1111.

14.0 PACKAGING INFORMATION

18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)

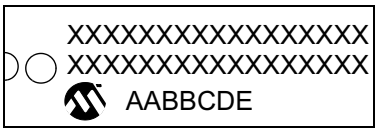


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing §	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

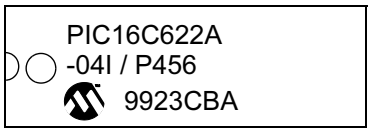
* Controlling Parameter
§ Significant Characteristic
JEDEC Equivalent: MO-036
Drawing No. C04-010

14.1 Package Marking Information

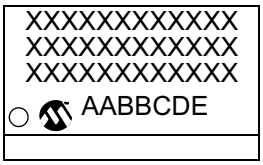
18-Lead PDIP



Example



18-Lead SOIC (.300")



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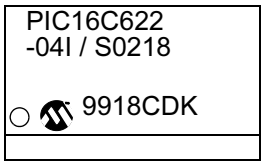
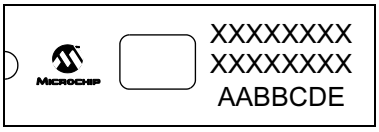


18-Lead CERDIP Windowed



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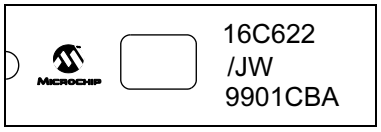
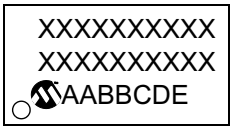
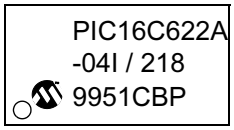


20-Lead SSOP



Example



Legend:	XX...X	Customer specific information*
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

* Standard PICmicro device marking consists of Microchip part number, year code, week code, and traceability code. For PICmicro device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

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